

Descum using PvaTepla ION10 with faraday cage:

measurement spot	Original Thickness (A)	Thickness after Descum	Difference in Thickness	Amount Oxygen	descum rate A/min	
B10	1	13106	10613	2493	50	249.3
	2	13165	11481	1684	50	168.4
	3	13092	10623	2469	50	246.9
	4	13059	9114	3945	50	394.5
	5	13091	10569	2522	50	252.2
B11	1	13096	7599	5497	100	549.7
	2	13126	9941	3185	100	318.5
	3	13111	8748	4363	100	436.3
	4	13072	5764	7308	100	730.8
	5	13116	9227	3889	100	388.9
B12	1	13193	6727	6466	150	646.6
	2	13172	9651	3521	150	352.1
	3	13216	7696	5520	150	552
	4	13158	4157	9001	150	900.1
	5	13232	8622	4610	150	461

spot 1: top of wafer
 spot 2: Left middle
 spot 3: middle of wafer
 spot 4: right middle of wafer
 spot 5: bottom of wafer

Wafer position in chamber is flat towards door(bottom) resist facing left side; spot 4 has highest position in chamber, spot 2 the lowest.

